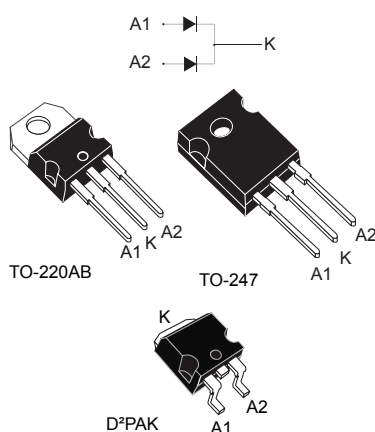


150 V power Schottky rectifier



Features

- High junction temperature capability
- Low leakage current
- High voltage capabilities
- Good trade off between leakage current and forward voltage drop
- Low thermal resistance
- High frequency operation
- ECOPACK®2 compliant for TO-220AB and TO-247, on demand for D²PAK

Applications

- Switching diode
- SMPS
- DC/DC converter
- Telecom power

Description

This dual center tab Schottky rectifier is suited for high frequency switched mode power supplies.

Packaged in TO-247, TO-220AB and D²PAK, this **STPS40150C** is optimized for use to enhance the reliability of the application.

Product status	
STPS40150C	
Product summary	
$I_{F(AV)}$	2 x 20 A
V_{RRM}	150 V
$T_{j(max.)}$	175 °C
$V_{F(typ.)}$	0.69 V

1 Characteristics

Table 1. Absolute ratings (limiting values, per diode at 25 °C, unless otherwise specified)

Symbol	Parameter			Value	Unit
V _{RRM}	Repetitive peak reverse voltage			150	V
I _{F(RMS)}	Forward rms current			60	A
I _{F(AV)}	Average forward current, δ = 0.5, square wave	T _C = 150 °C	Per diode	20	A
		T _C = 145 °C	Per device	40	
I _{FSM}	Surge non repetitive forward current	t _p = 10 ms sinusoidal		250	A
P _{ARM}	Repetitive peak avalanche power	t _p = 10 μs, T _j = 125 °C		1015	W
T _{stg}	Storage temperature range			-65 to +175	°C
T _j	Maximum operating junction temperature ⁽¹⁾			+175	°C

1. $(dP_{tot}/dT_j) < (1/R_{th(j-a)})$ condition to avoid thermal runaway for a diode on its own heatsink.

Table 2. Thermal resistance parameters

Symbol	Parameter		Value	Unit
			Max.	
$R_{th(j-c)}$	Junction to case	Per diode	1.20	°C/W
		Total	0.85	
$R_{th(c)}$	Coupling		0.50	°C/W

When the diodes 1 and 2 are used simultaneously:

$$\Delta T_j (\text{diode1}) = P_{(\text{diode1})} \times R_{th(j-c)} (\text{per diode}) + P_{(\text{diode2})} \times R_{th(c)}$$

Table 3. Static electrical characteristics (per diode)

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25\text{ °C}$	$V_R = V_{RRM}$	-	2	8	μA
		$T_j = 125\text{ °C}$		-	2	11	mA
$V_F^{(2)}$	Forward voltage drop	$T_j = 25\text{ °C}$	$I_F = 20\text{ A}$	-		0.92	V
		$T_j = 125\text{ °C}$		-	0.69	0.75	
		$T_j = 25\text{ °C}$	$I_F = 40\text{ A}$	-		1.00	
		$T_j = 125\text{ °C}$		-	0.79	0.86	

1. Pulse test: $t_p = 5\text{ ms}$, $\delta < 2\%$

2. Pulse test: $t_p = 380\text{ }\mu\text{s}$, $\delta < 2\%$

To evaluate the conduction losses, use the following equation: $P = 0.64 \times I_{F(AV)} + 0.0055 \times I_F^2 (\text{RMS})$

For more information, please refer to the following application notes related to the power losses :

- AN604: Calculation of conduction losses in a power rectifier
- AN4021: Calculation of reverse losses on a power diode

1.1 Characteristics (curves)

Figure 1. Average forward power dissipation versus average forward current (per diode)

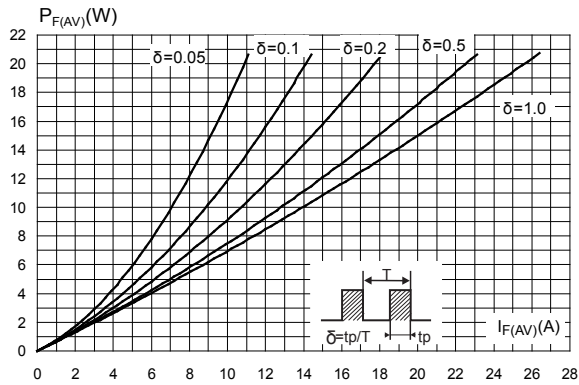


Figure 2. Average forward current versus ambient temperature ($\delta = 0.5$, per diode)

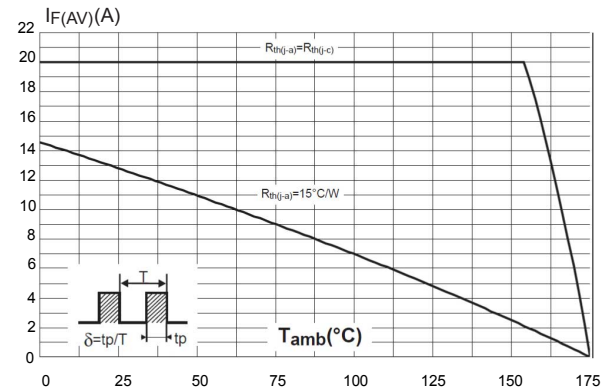


Figure 3. Normalized avalanche power derating versus pulse duration ($T_j = 125^\circ\text{C}$)

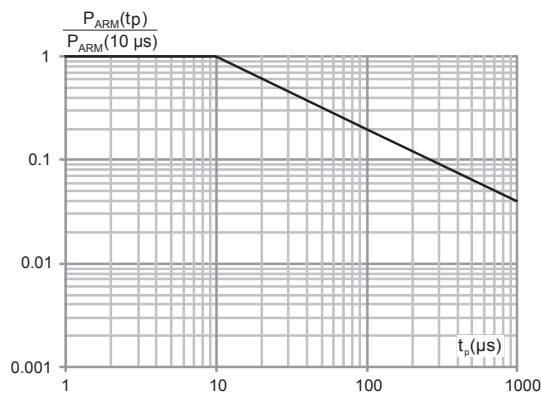


Figure 4. Relative variation of thermal impedance junction to case versus pulse duration

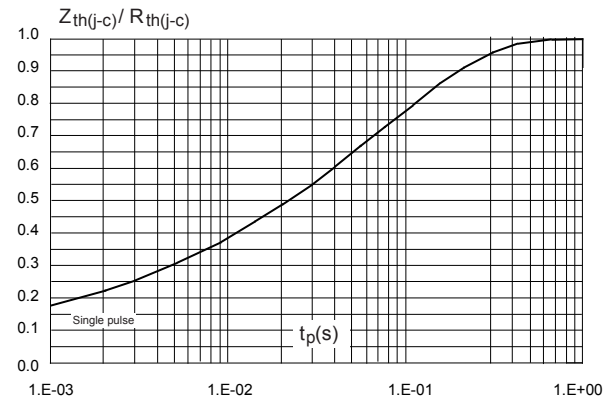


Figure 5. Reverse leakage current versus reverse voltage applied (typical values, per diode)

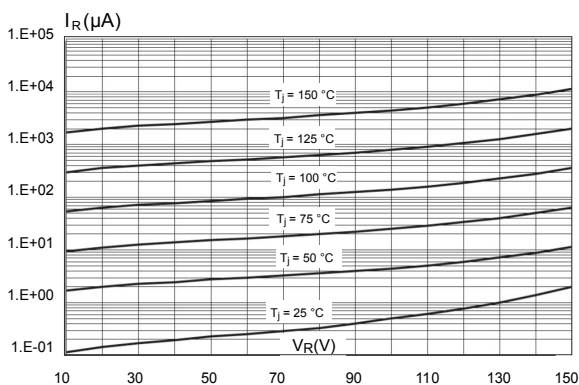


Figure 6. Junction capacitance versus reverse voltage applied (typical values, per diode)

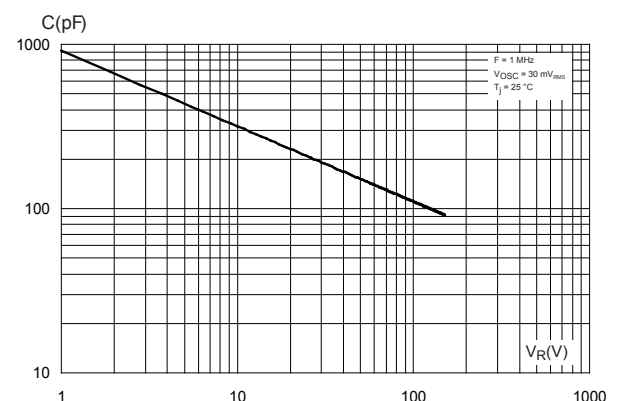


Figure 7. Forward voltage drop versus forward current (per diode)

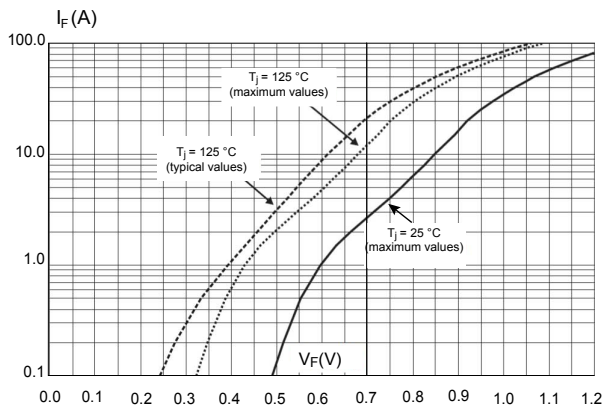
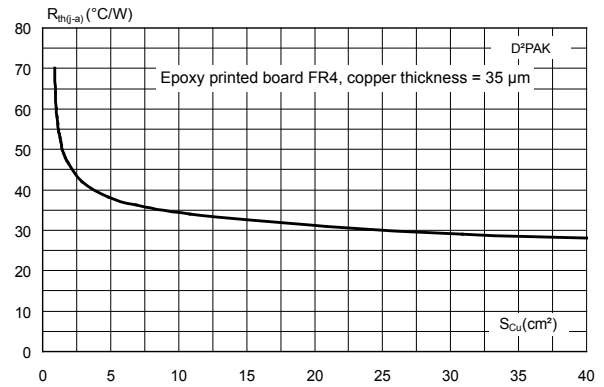


Figure 8. Thermal resistance junction to ambient versus copper surface under tab



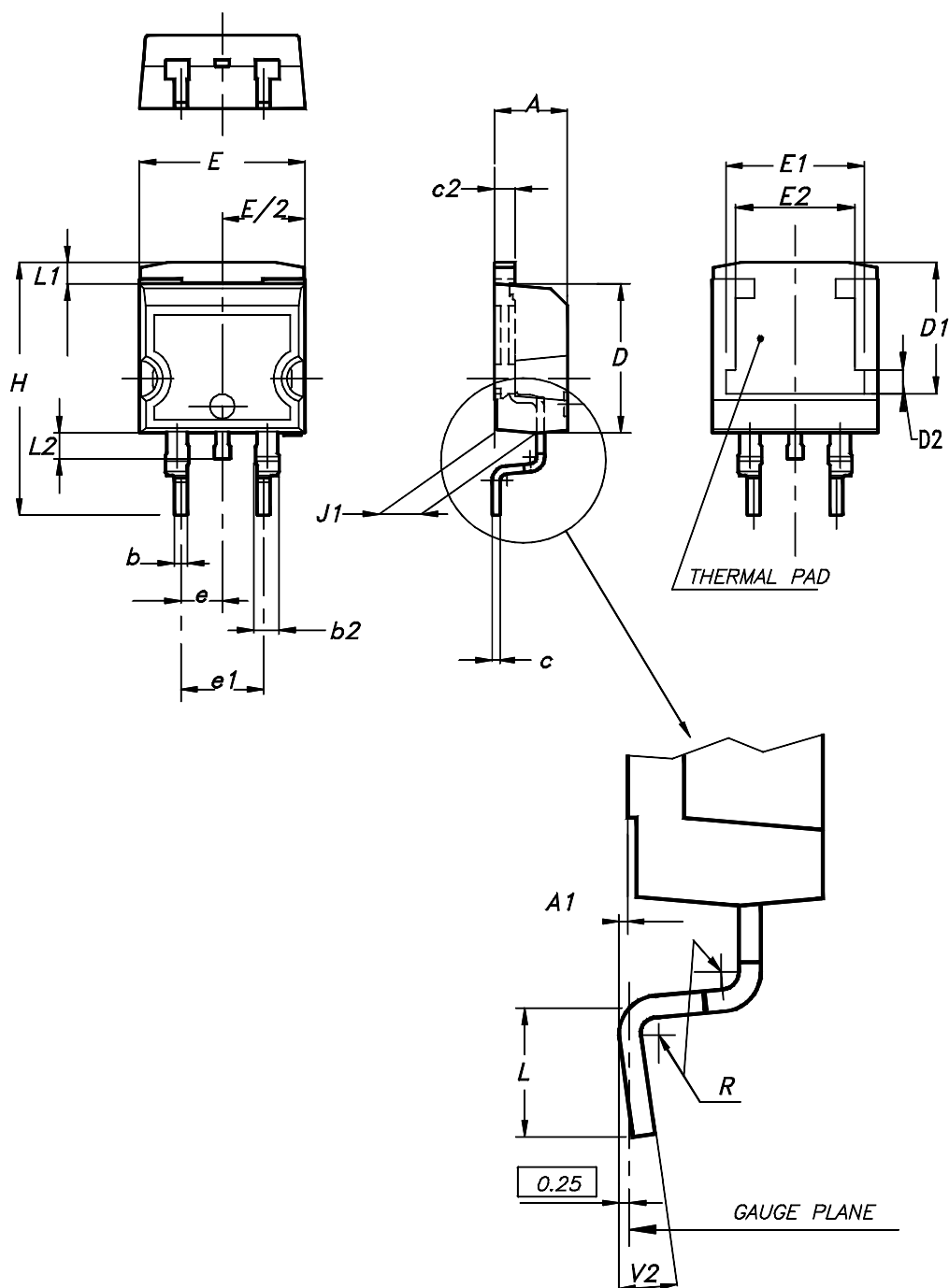
2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

2.1 D²PAK package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)

Figure 9. D²PAK package outline

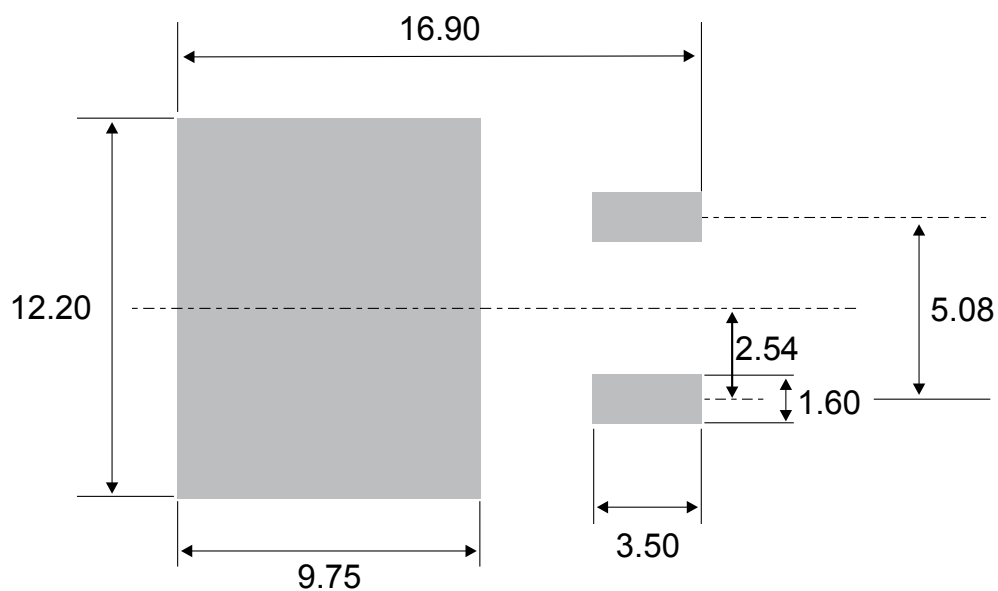


Note: This package drawing may slightly differ from the physical package. However, all the specified dimensions are guaranteed.

Table 4. D²PAK package mechanical data

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.36	4.60	0.172	0.181
A1	0.00	0.25	0.000	0.010
b	0.70	0.93	0.028	0.037
b2	1.14	1.70	0.045	0.067
c	0.38	0.69	0.015	0.027
c2	1.19	1.36	0.047	0.053
D	8.60	9.35	0.339	0.368
D1	6.90	8.00	0.272	0.311
D2	1.10	1.50	0.043	0.060
E	10.00	10.55	0.394	0.415
E1	8.10	8.90	0.319	0.346
E2	6.85	7.25	0.266	0.282
e	2.54 typ.		0.100	
e1	4.88	5.28	0.190	0.205
H	15.00	15.85	0.591	0.624
J1	2.49	2.90	0.097	0.112
L	1.90	2.79	0.075	0.110
L1	1.27	1.65	0.049	0.065
L2	1.30	1.78	0.050	0.070
R	0.4 typ.		0.015	
V2	0°	8°	0°	8°

Figure 10. D²PAK recommended footprint (dimensions in mm)



2.2 TO-247 package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)
- Recommended torque value: 0.8 N·m
- Maximum torque value: 1.0 N·m

Figure 11. TO-247 package outline

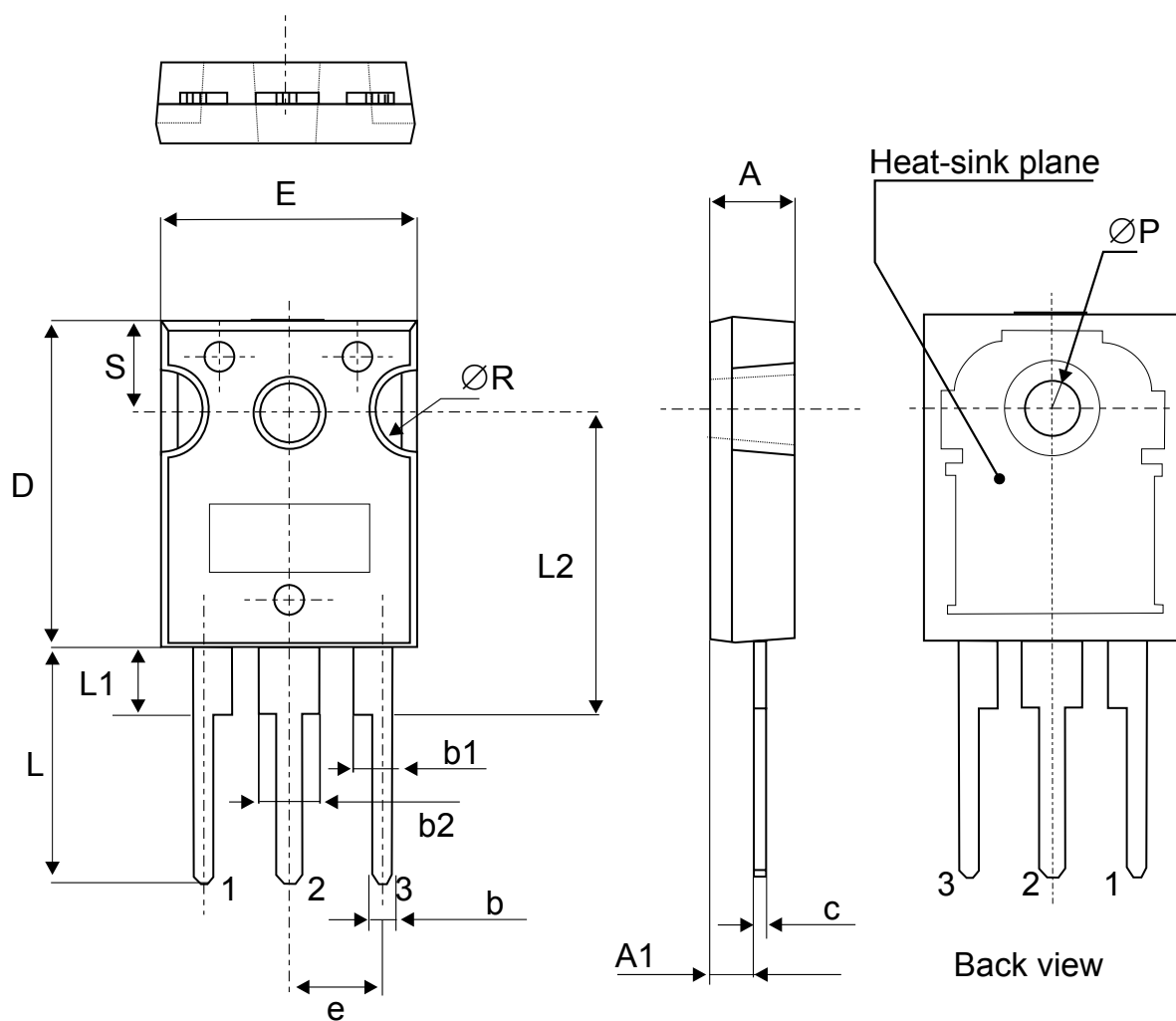


Table 5. TO-247 package mechanical data

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.85		5.15	0.191		0.203
A1	2.20		2.60	0.086		0.102
b	1.00		1.40	0.039		0.055
b1	2.00		2.40	0.078		0.094
b2	3.00		3.40	0.118		0.133
c	0.40		0.80	0.015		0.031
D	19.85		20.15	0.781		0.793
E	15.45		15.75	0.608		0.620
e	5.30	5.45	5.60	0.209	0.215	0.220
L	14.20		14.80	0.559		0.582
L1	3.70		4.30	0.145		0.169
L2		18.50			0.728	
ØP	3.55		3.65	0.139		0.143
ØR	4.50		5.50	0.177		0.217
S	5.30	5.50	5.70	0.209	0.216	0.224

1. Inches dimensions given for reference only

2.3 TO-220AB package information

- Epoxy meets UL 94,V0
- Cooling method: by conduction (C)
- Recommended torque value: 0.55 N·m
- Maximum torque value: 0.70 N·m

Figure 12. TO-220AB package outline

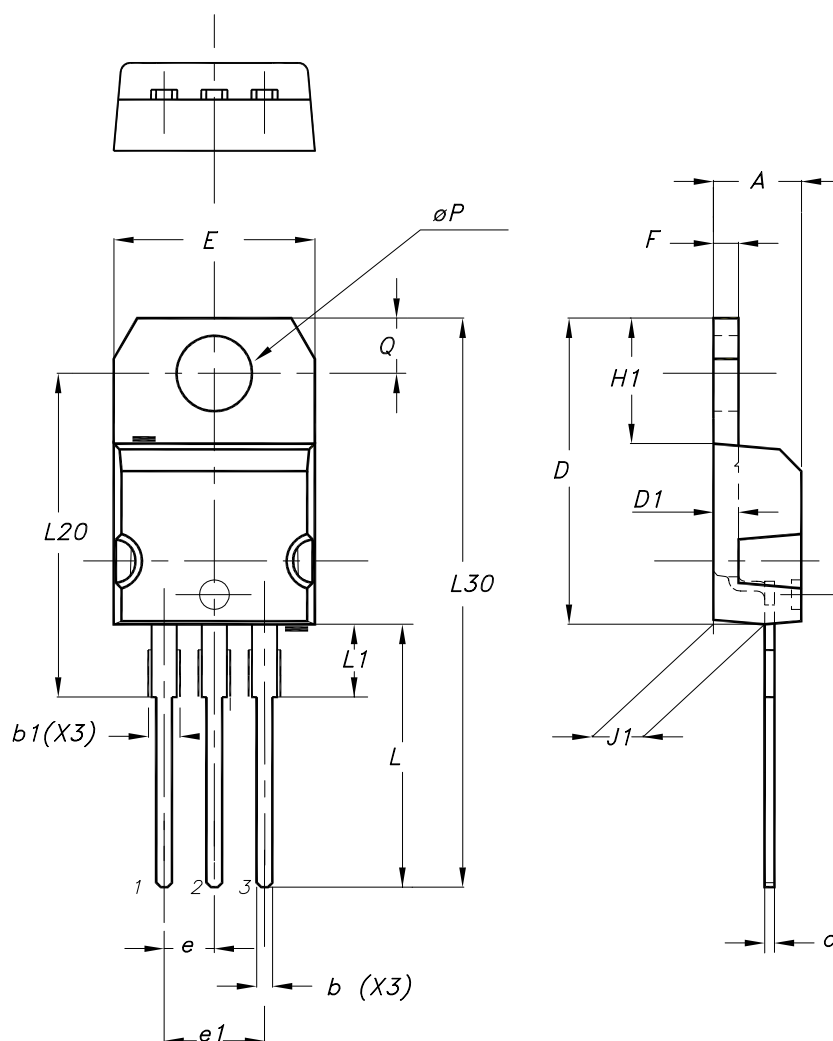


Table 6. TO-220AB package mechanical data

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
b	0.61	0.88	0.240	0.035
b1	1.14	1.55	0.045	0.061

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
c	0.48	0.70	0.019	0.028
D	15.25	15.75	0.600	0.620
D1	1.27 typ.		0.050 typ.	
E	10.00	10.40	0.394	0.409
e	2.40	2.70	0.094	0.106
e1	4.95	5.15	0.195	0.203
F	1.23	1.32	0.048	0.052
H1	6.20	6.60	0.244	0.260
J1	2.40	2.72	0.094	0.107
L	13.00	14.00	0.512	0.551
L1	3.50	3.93	0.138	0.155
L20	16.40 typ.		0.646 typ.	
L30	28.90 typ.		1.138 typ.	
θP	3.75	3.85	0.148	0.152
Q	2.65	2.95	0.104	0.116

3 Ordering information

Table 7. Order code

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STPS40150CT	STPS40150CT	TO-220AB	1.95 g	50	Tube
STPS40150CW	STPS40150CW	TO-247	4.36 g	30	Tube
STPS40150CG	STPS40150CG	D ² PAK	1.38 g	50	Tube
STPS40150CG-TR	STPS40150CG	D ² PAK	1.38 g	1000	Tape and reel

Revision history

Table 8. Document revision history

Date	Revision	Changes
07-Sep-2006	1	First issue.
01-Jun-2018	2	Updated P_{ARM} value and removed "Normalized avalanche power derating" curves. Removed I ² PAK package information.

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